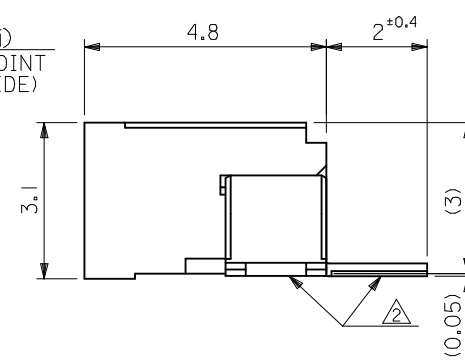
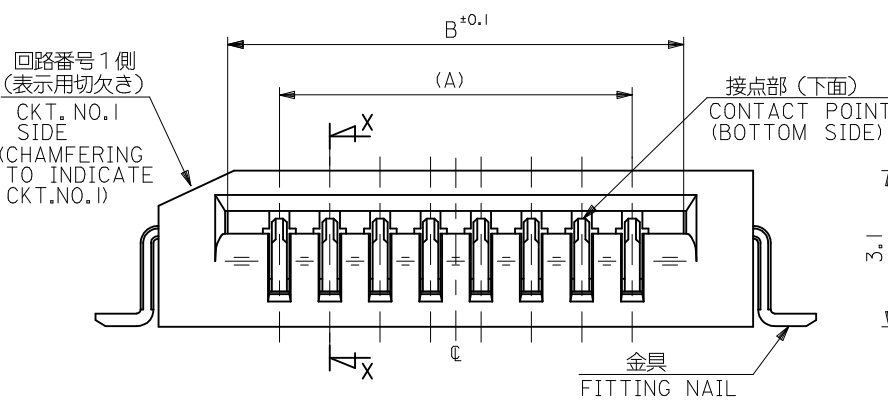
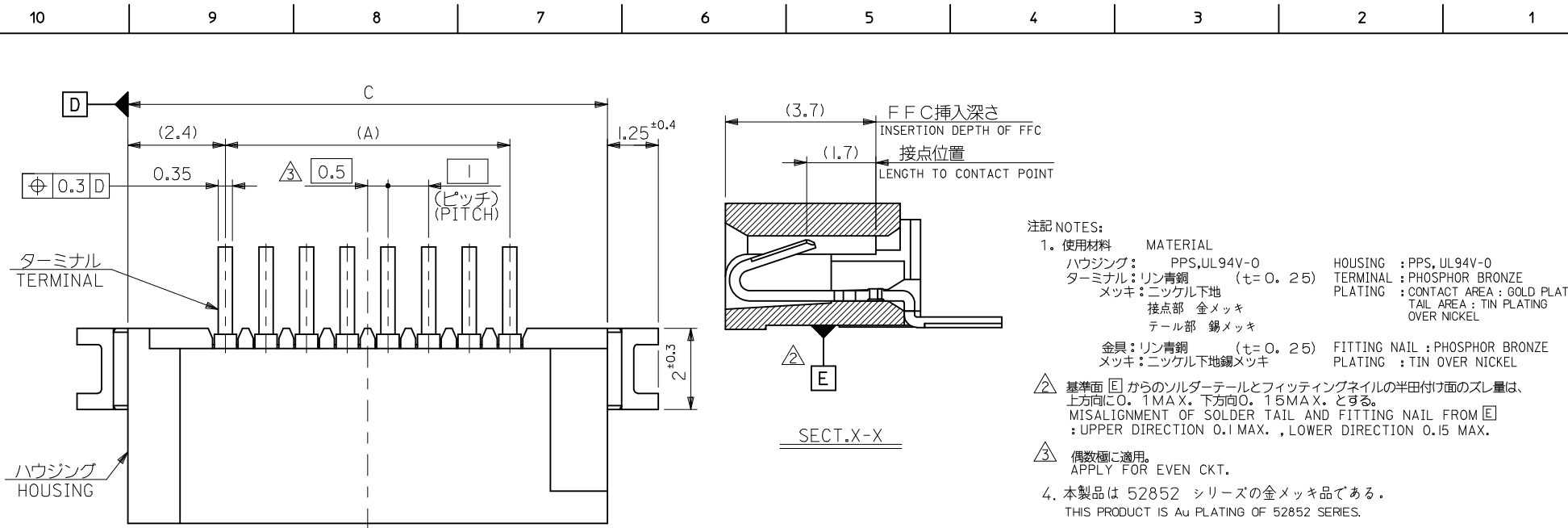




注記 NOTES:

1. 使用材料 MATERIAL
ハウジング: PPS,UL94V-0
ターミナル: リン青銅 (τ=0.25)
メッキ: ニッケル下地
接点部 金メッキ
テール部 錫メッキ
金具: リン青銅 (τ=0.25)
メッキ: ニッケル下地銅メッキ

HOUSING : PPS,UL94V-0
TERMINAL : PHOSPHOR BRONZE
PLATING : CONTACT AREA : GOLD PLATING
TAIL AREA : TIN PLATING
OVER NICKEL
FITTING NAIL : PHOSPHOR BRONZE
PLATING : TIN OVER NICKEL

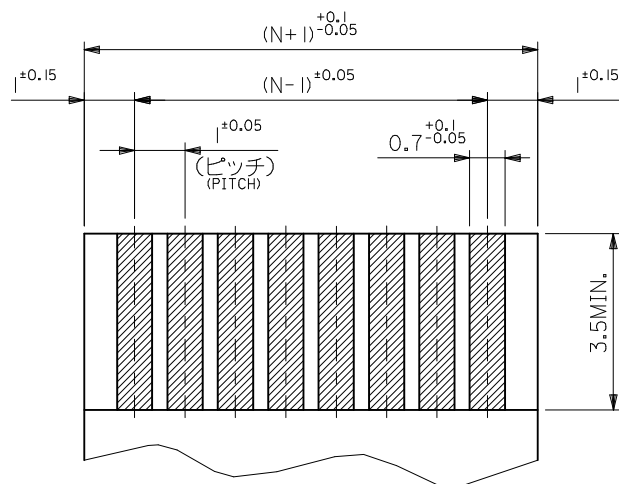
基準面 E からのもルダールとフィッティングネイルの半田付け面のズレ量は、
上方向に0.1MAX. 下方向0.15MAX. とする。
MISALIGNMENT OF SOLDER TAIL AND FITTING NAIL FROM E
: UPPER DIRECTION 0.1 MAX. , LOWER DIRECTION 0.15 MAX.

偶数極に適用。
APPLY FOR EVEN CKT.

4. 本製品は 52852 シリーズの金メッキ品である。
THIS PRODUCT IS Au PLATING OF 52852 SERIES.

32.8	30.05	28	52852-2971	29
29.8	27.05	25	52852-2671	26
27.8	25.05	23	52852-2471	24
19.8	17.05	15	52852-1671	16
18.8	16.05	14	52852-1571	15
17.8	15.05	13	52852-1471	14
16.8	14.05	12	52852-1371	13
15.8	13.05	11	52852-1271	12
7.8	5.05	3	52852-0471	4
C	B	A	MATERIAL NO.	極数 CIRCUIT

REVISED EC NO: J2014-0324 DRWN: MTAKAHASHI 04/2013/08/20 CHKD: KTAHASHI 2013/08/20 APPR: YNOGAWA 2013/08/27	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	MODEL NO. J2032-**-71 THIRD ANGLE PROJECTION	
		10 UNDER	± 0.2	M. NABEI	DATE '05/08/23	TITLE 1.0 FFC CONN NON ZIF SMT RA (BOTTOM CONTACT) -LEAD FREE-			
		10 OVER 30 UNDER	± 0.25	CHECKED BY K. TOYODA	DATE '05/08/23				
		30 OVER	± 0.3	APPROVED BY N. UKITA	DATE '05/08/23				
		ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.			SHEET NO.
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-52852-012			1 OF 2	
	REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							



(仕上がり厚さ 0.3 ± 0.03)
THICKNESS
適合FPC/FFC推奨寸法
APPLICABLE FPC/FFC
RECOMMENDED DIMENSION.

FPC/FFCについて:

打抜き方向は導体側から補強板側を推奨いたします。

ABOUT FPC/FFC

RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.

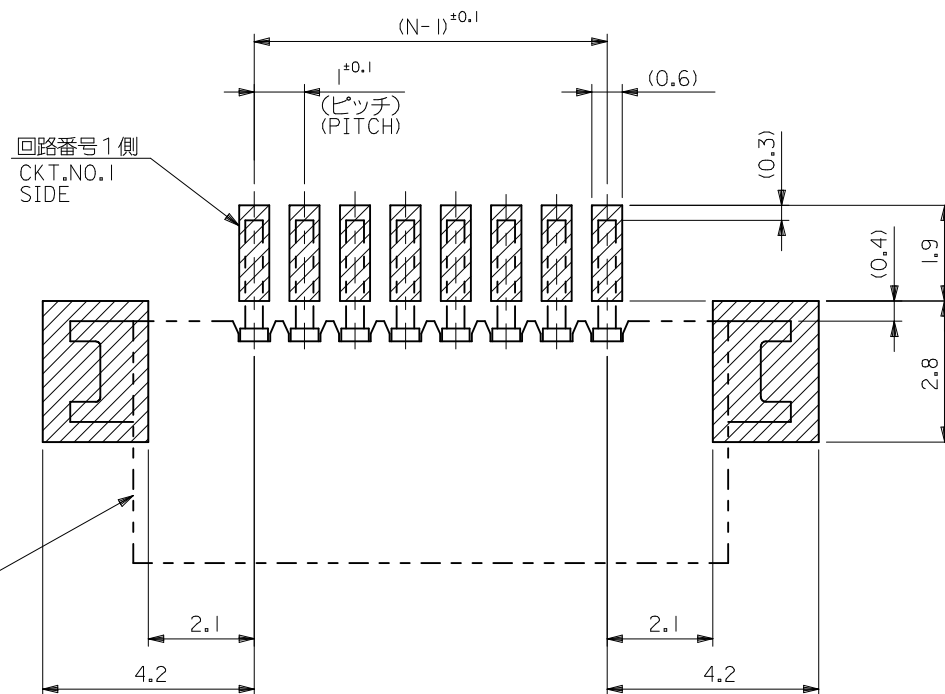
FPCについて:

補強フィルム材質はポリイミドを推奨します。

接着剤は熱硬化接着剤を推奨します。

ABOUT FPC

RECOMMENDED MATERIAL :
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT



コネクタ位置
CONNECTOR
POSITION

参考基板レイアウト (マウント面)

RECOMMENDED P.C.BOARD
PATTERN DIMENSION. (REF.)
(MOUNTING AREA)

REVISED EC NO: J2014-0324 DRWN:MTAKAHASHI 04/2013/08/20 CHKD:K.TAKAHASHI 2013/08/20 APPR: YNOGAWA 2013/08/27	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	± 0.2	DRAWN BY M. NABEI	DATE '05/08/23	TITLE 1.0 FFC CONN NON ZIF SMT RA (BOTTOM CONTACT) -LEAD FREE- molex	DOCUMENT NO. SD-52852-012	SHEET NO. 2 OF 2	
		10 OVER 30 UNDER	± 0.25	CHECKED BY K. TOYODA	DATE '05/08/23				
		30 OVER	± 0.3	APPROVED BY N. UKITA	DATE '05/08/23				
		ANGULAR ±3 °		MATERIAL NO. SEE SHEET 1 OF 2					
	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				